


**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	ADG/17/10180	
<b>1.3 Title of PCN</b>	EHD7 and OFT Technology Front and Back Metal Capacity Extension - Ang Mo Kio (Singapore)	
<b>1.4 Product Category</b>	Power MOSFET	
<b>1.5 Issue date</b>	2017-04-05	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	ROBERTSON HEATHER
<b>2.1.2 Phone</b>	+1 8475853058
<b>2.1.3 Email</b>	heather.robertson@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Mario Antonio ALEO
<b>2.1.2 Marketing Manager</b>	Maurizio GIUDICE,Riccardo NICOLOSO
<b>2.1.3 Quality Manager</b>	Vincenzo MILITANO

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Transfer of a full process or process brick (process step, control plan, recipes) from one site to another site	Wafer fabrication site	Ang Mo Kio (Singapore)

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	STripFET™ F6 (EHD7) and STripFET™ F7 (OFT) technology Wafer Front and Back Metal Finishing process and EWS is done in Catania (Italy) and/or HHGrace (China)	STripFET™ F6 (EHD7) and STripFET™ F7 (OFT) technology Wafer Front and Back Metal Finishing process and EWS is done in also in Ang Mo Kio (Singapore)
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	no impact	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	Capacity Extension
<b>5.2 Customer Benefit</b>	CAPACITY INCREASE

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	by FG code and Q.A. number
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2017-03-23
<b>7.2 Intended start of delivery</b>	2017-10-10
<b>7.3 Qualification sample available?</b>	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>	10180 Rel02-17.pdf		
<b>8.2 Qualification report and qualification results</b>	Available (see attachment)	<b>Issue Date</b>	2017-04-05

**9. Attachments (additional documentations)**

10180 Public product.pdf  
10180 EHD7 and OFT Technology Front and Back Metal Capacity Extension - Ang Mo Kio (Singapore).pdf  
10180 Rel02-17.pdf

**10. Affected parts**

10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STL135N8F7AG	
	STL140N4F7AG	
	STL190N4F7AG	



## Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

**PCN Title :** EHD7 and OFT Technology Front and Back Metal Capacity Extension - Ang Mo Kio (Singapore)

**PCN Reference :** ADG/17/10180

**Subject :** Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STL135N8F7AG		
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